

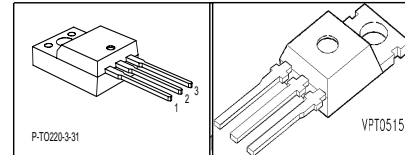
Cool MOS™ Power Transistor

Feature

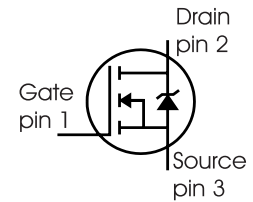
- New revolutionary high voltage technology
- Ultra low gate charge
- Periodic avalanche rated
- Extreme dv/dt rated
- Ultra low effective capacitances
- Improved transconductance
- PG-TO-220-3-31: Fully isolated package (2500 VAC; 1 minute)
- Pb-free lead plating; RoHS compliant
- Qualified according to JEDEC⁰⁾ for target applications

V_{DS}	800	V
$R_{DS(on)}$	0.45	Ω
I_D	11	A

PG-TO220-3-31 PG-TO220



Type	Package	Ordering Code	Marking
SPP11N80C3	PG-TO220	Q67040-S4438	11N80C3
SPA11N80C3	PG-TO220-3-31	SP000216320	11N80C3



Maximum Ratings

Parameter	Symbol	Value		Unit
		SPP	SPA	
Continuous drain current $T_C = 25\text{ }^\circ\text{C}$ $T_C = 100\text{ }^\circ\text{C}$	I_D	11 7.1	111) 7.11)	A
Pulsed drain current, t_p limited by T_{jmax}	$I_{D\text{ puls}}$	33	33	A
Avalanche energy, single pulse $I_D=2.2\text{A}, V_{DD}=50\text{V}$	E_{AS}	470	470	mJ
Avalanche energy, repetitive t_{AR} limited by T_{jmax} ²⁾ $I_D=11\text{A}, V_{DD}=50\text{V}$	E_{AR}	0.2	0.2	
Avalanche current, repetitive t_{AR} limited by T_{jmax}	I_{AR}	11	11	A
Gate source voltage	V_{GS}	± 20	± 20	V
Gate source voltage AC ($f > 1\text{Hz}$)	V_{GS}	± 30	± 30	
Power dissipation, $T_C = 25\text{ }^\circ\text{C}$	P_{tot}	156	41	W
Operating and storage temperature	T_j, T_{stg}	-55...+150		$^\circ\text{C}$

Maximum Ratings

Parameter	Symbol	Value	Unit
Drain Source voltage slope $V_{DS} = 640 \text{ V}, I_D = 11 \text{ A}, T_j = 125 \text{ }^\circ\text{C}$	dv/dt	50	V/ns

Thermal Characteristics

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Thermal resistance, junction - case	R_{thJC}	-	-	0.8	K/W
Thermal resistance, junction - case, FullPAK	$R_{thJC \text{ FP}}$	-	-	3.7	
Thermal resistance, junction - ambient, leaded	R_{thJA}	-	-	62	
Thermal resistance, junction - ambient, FullPAK	$R_{thJA \text{ FP}}$	-	-	80	
Soldering temperature, wavesoldering 1.6 mm (0.063 in.) from case for 10s ³)	T_{sold}	-	-	260	$^\circ\text{C}$

Electrical Characteristics, at $T_j=25^\circ\text{C}$ unless otherwise specified

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Drain-source breakdown voltage	$V_{(BR)DSS}$	$V_{GS}=0\text{V}, I_D=0.25\text{mA}$	800	-	-	V
Drain-Source avalanche breakdown voltage	$V_{(BR)DS}$	$V_{GS}=0\text{V}, I_D=11\text{A}$	-	870	-	
Gate threshold voltage	$V_{GS(th)}$	$I_D=680\mu\text{A}, V_{GS}=V_{DS}$	2.1	3	3.9	
Zero gate voltage drain current	I_{DSS}	$V_{DS}=800\text{V}, V_{GS}=0\text{V},$ $T_j=25^\circ\text{C}$ $T_j=150^\circ\text{C}$	- -	0.5 -	20 200	μA
Gate-source leakage current	I_{GSS}	$V_{GS}=20\text{V}, V_{DS}=0\text{V}$	-	-	100	nA
Drain-source on-state resistance	$R_{DS(on)}$	$V_{GS}=10\text{V}, I_D=7.1\text{A}$ $T_j=25^\circ\text{C}$ $T_j=150^\circ\text{C}$	- -	0.39 1.1	0.45 -	Ω
Gate input resistance	R_G	$f=1\text{MHz}, \text{open drain}$	-	0.7	-	

Electrical Characteristics

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Transconductance	g_{fs}	$V_{DS} \geq 2 \cdot I_D \cdot R_{DS(on)max}$, $I_D = 7.1A$	-	7.5	-	S
Input capacitance	C_{iss}	$V_{GS} = 0V$, $V_{DS} = 25V$, $f = 1MHz$	-	1600	-	pF
Output capacitance	C_{oss}		-	800	-	
Reverse transfer capacitance	C_{rss}		-	40	-	
Effective output capacitance, ⁴⁾ energy related	$C_{o(er)}$	$V_{GS} = 0V$, $V_{DS} = 0V$ to 480V	-	44.3	-	
Effective output capacitance, ⁵⁾ time related	$C_{o(tr)}$		-	33.9	-	
Turn-on delay time	$t_{d(on)}$	$V_{DD} = 400V$, $V_{GS} = 0/10V$, $I_D = 11A$, $R_G = 7.5\Omega$	-	25	-	ns
Rise time	t_r		-	15	-	
Turn-off delay time	$t_{d(off)}$		-	72	82	
Fall time	t_f		-	7	10	

Gate Charge Characteristics

Gate to source charge	Q_{gs}	$V_{DD} = 640V$, $I_D = 11A$	-	6	-	nC
Gate to drain charge	Q_{gd}		-	25	-	
Gate charge total	Q_g	$V_{DD} = 640V$, $I_D = 11A$, $V_{GS} = 0$ to 10V	-	50	60	
Gate plateau voltage	$V_{(plateau)}$	$V_{DD} = 640V$, $I_D = 11A$	-	6	-	V

⁰J-STD20 and JESD22

¹Limited only by maximum temperature

²Repetitive avalanche causes additional power losses that can be calculated as $P_{AV} = E_{AR} \cdot f$.

³Soldering temperature for TO-263: 220°C, reflow

⁴ $C_{o(er)}$ is a fixed capacitance that gives the same stored energy as C_{oss} while V_{DS} is rising from 0 to 80% V_{DSS} .

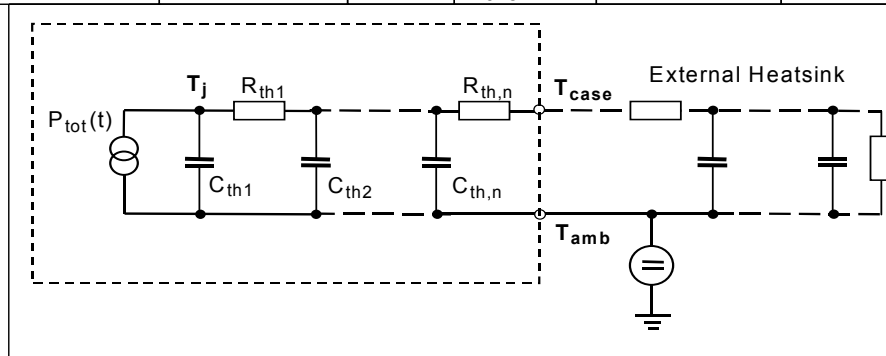
⁵ $C_{o(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 to 80% V_{DSS} .

Electrical Characteristics

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Inverse diode continuous forward current	I_S	$T_C=25^\circ\text{C}$	-	-	11	A
Inverse diode direct current, pulsed	I_{SM}		-	-	33	
Inverse diode forward voltage	V_{SD}	$V_{GS}=0\text{V}, I_F=I_S$	-	1	1.2	V
Reverse recovery time	t_{rr}	$V_R=640\text{V}, I_F=I_S,$	-	550	-	ns
Reverse recovery charge	Q_{rr}	$di_F/dt=100\text{A}/\mu\text{s}$	-	10	-	μC
Peak reverse recovery current	I_{rrm}		-	33	-	A
Peak rate of fall of reverse recovery current	di_{rr}/dt	$T_j=25^\circ\text{C}$	-	1000	-	$\text{A}/\mu\text{s}$

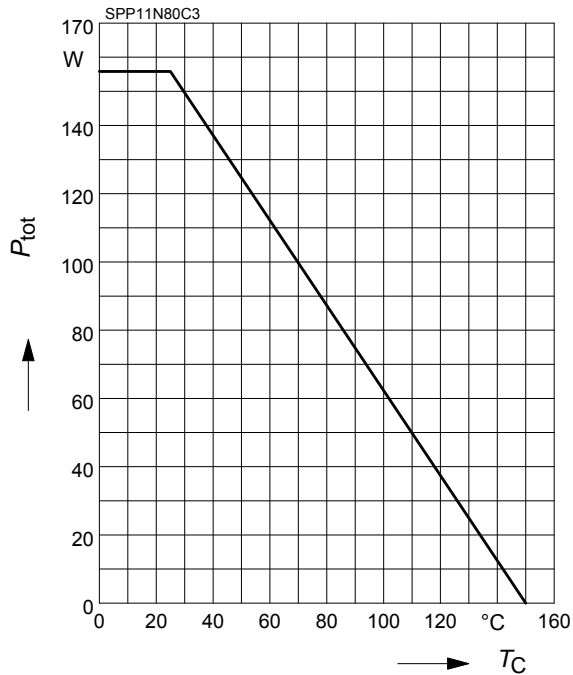
Typical Transient Thermal Characteristics

Symbol	Value		Unit	Symbol	Value		Unit
	SPP	SPA			SPP	SPA	
R_{th1}	0.012	0.012	K/W	C_{th1}	0.0002493	0.0002493	Ws/K
R_{th2}	0.023	0.023		C_{th2}	0.0009399	0.0009399	
R_{th3}	0.043	0.043		C_{th3}	0.001298	0.001298	
R_{th4}	0.154	0.176		C_{th4}	0.003617	0.003617	
R_{th5}	0.175	0.371		C_{th5}	0.009186	0.00802	
R_{th6}	0.071	2.522		C_{th6}	0.074	0.412	



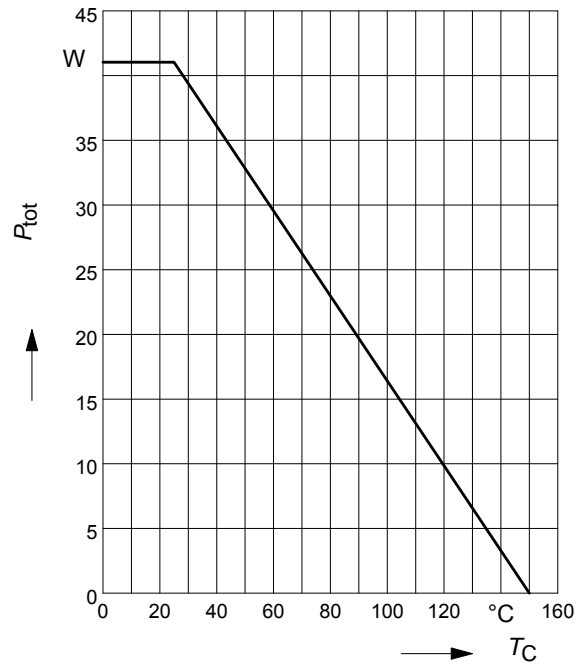
1 Power dissipation

$P_{tot} = f(T_C)$



2 Power dissipation FullPAK

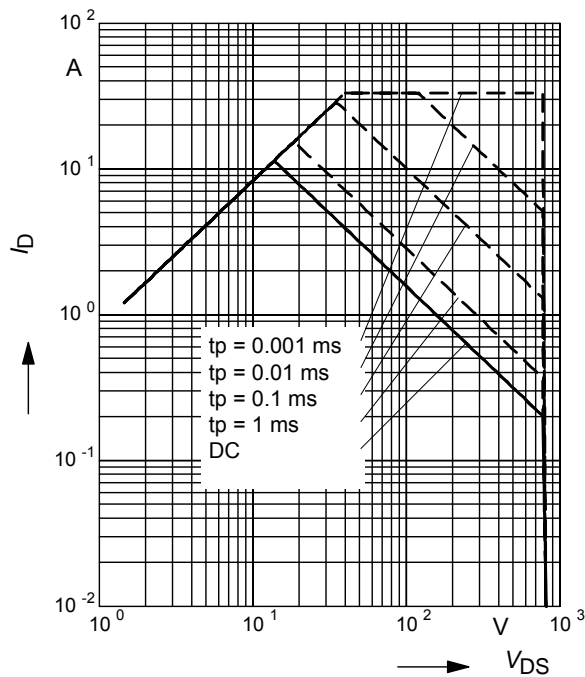
$P_{tot} = f(T_C)$



3 Safe operating area

$I_D = f(V_{DS})$

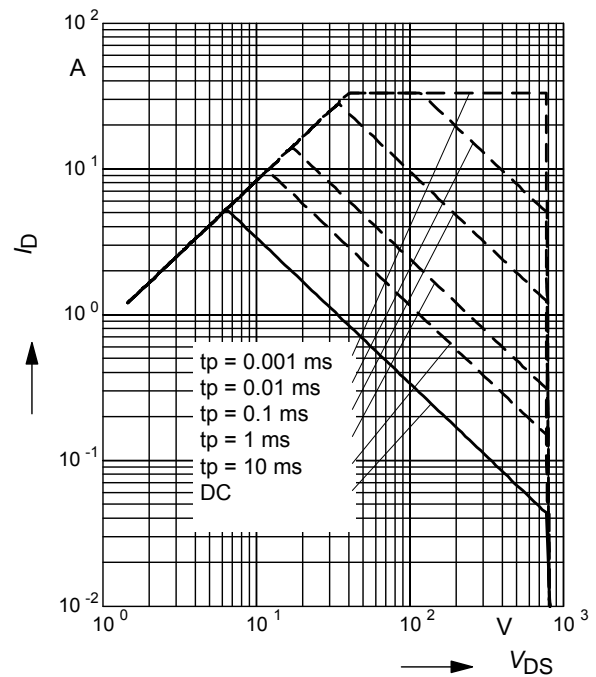
parameter : $D = 0$, $T_C = 25^\circ\text{C}$



4 Safe operating area FullPAK

$I_D = f(V_{DS})$

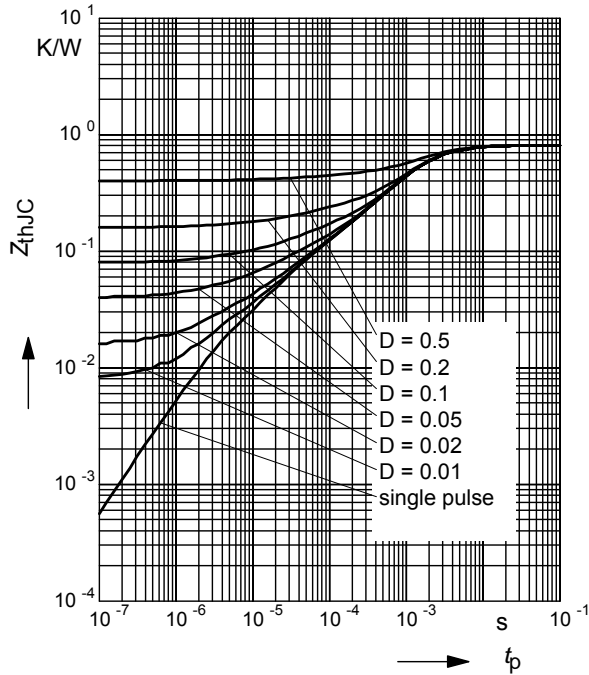
parameter: $D = 0$, $T_C = 25^\circ\text{C}$



5 Transient thermal impedance

$Z_{thJC} = f(t_p)$

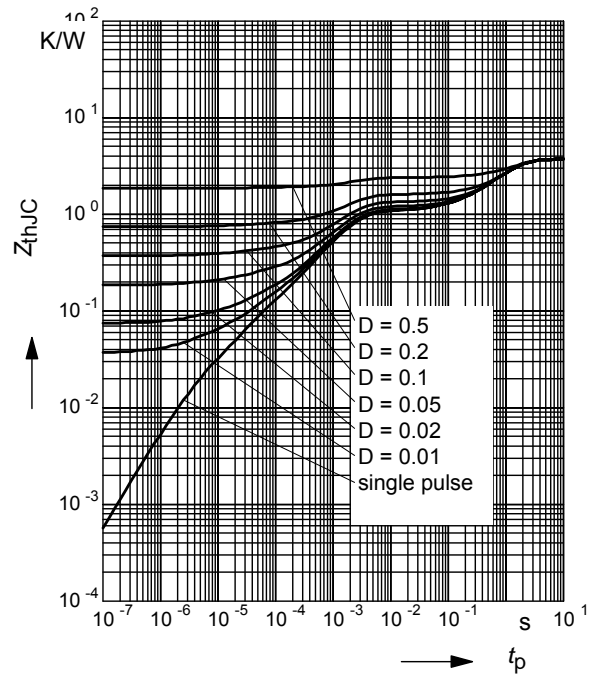
parameter: $D = t_p/T$



6 Transient thermal impedance FullPAK

$Z_{thJC} = f(t_p)$

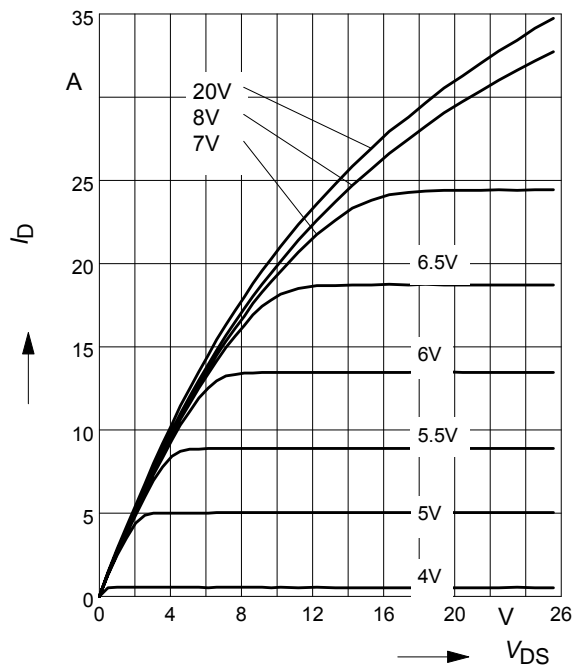
parameter: $D = t_p/t$



7 Typ. output characteristic

$I_D = f(V_{DS}); T_j = 25^\circ C$

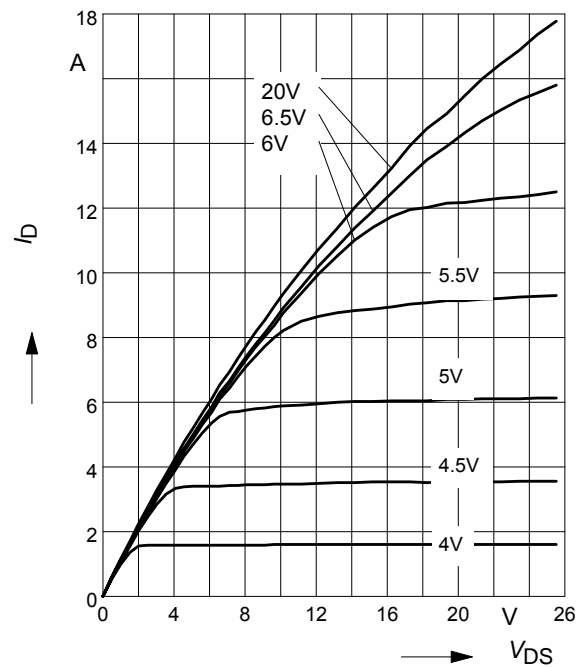
parameter: $t_p = 10 \mu s, V_{GS}$



8 Typ. output characteristic

$I_D = f(V_{DS}); T_j = 150^\circ C$

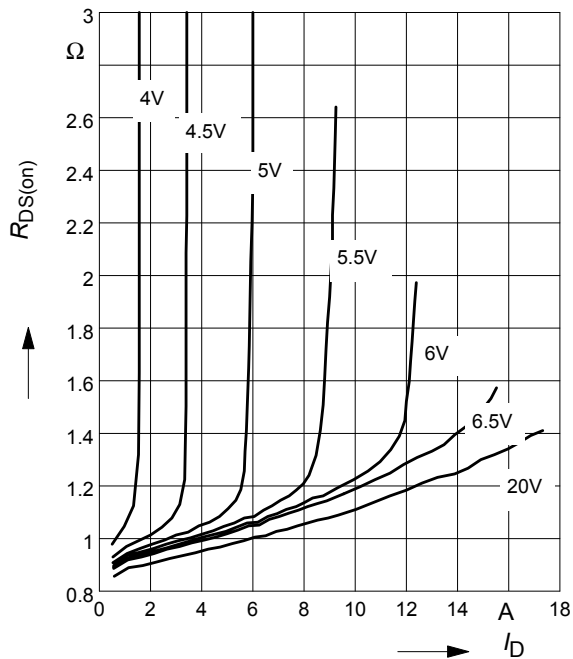
parameter: $t_p = 10 \mu s, V_{GS}$



9 Typ. drain-source on resistance

$$R_{DS(on)} = f(I_D)$$

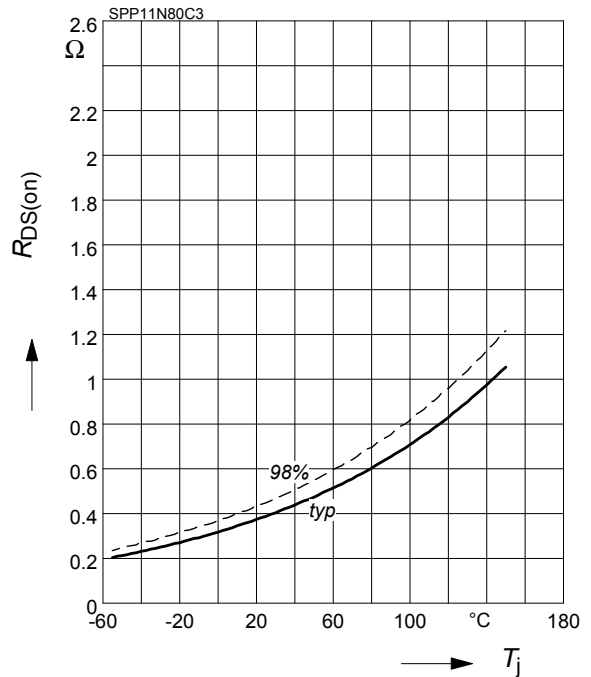
parameter: $T_j = 150^\circ\text{C}$, V_{GS}



10 Drain-source on-state resistance

$$R_{DS(on)} = f(T_j)$$

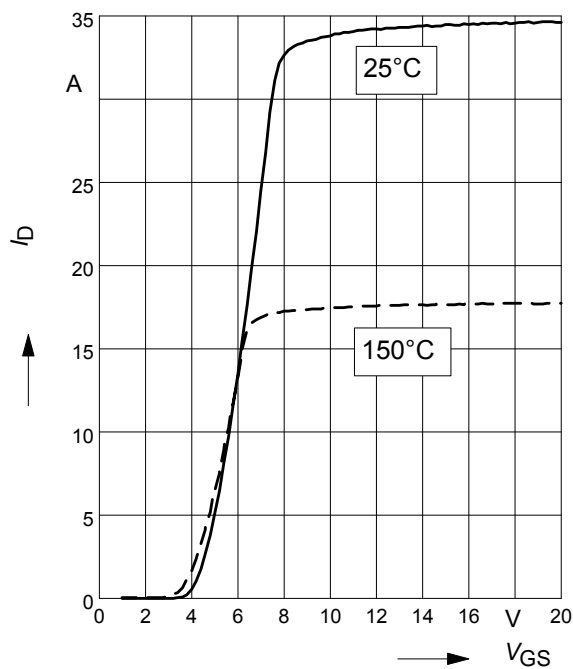
parameter: $I_D = 7.1\text{ A}$, $V_{GS} = 10\text{ V}$



11 Typ. transfer characteristics

$$I_D = f(V_{GS}); V_{DS} \geq 2 \times I_D \times R_{DS(on)max}$$

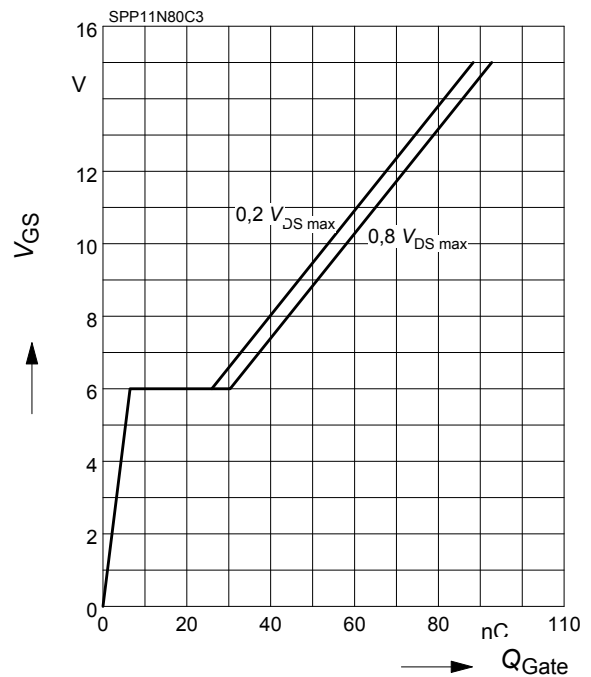
parameter: $t_p = 10\ \mu\text{s}$



12 Typ. gate charge

$$V_{GS} = f(Q_{Gate})$$

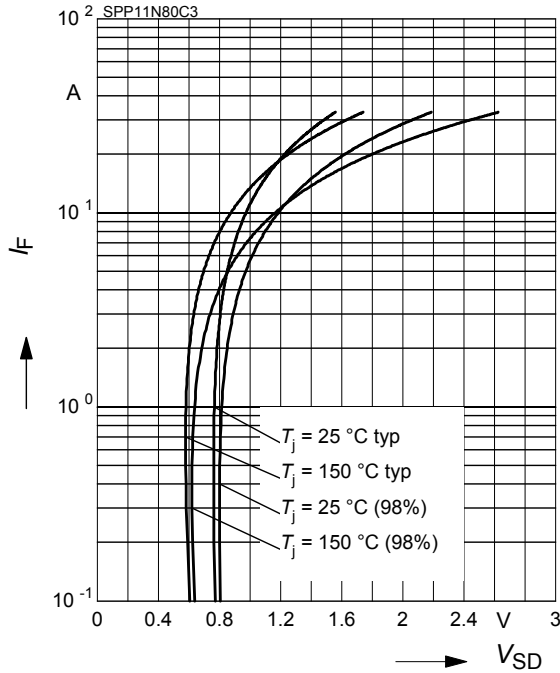
parameter: $I_D = 11\text{ A pulsed}$



13 Forward characteristics of body diode

$I_F = f(V_{SD})$

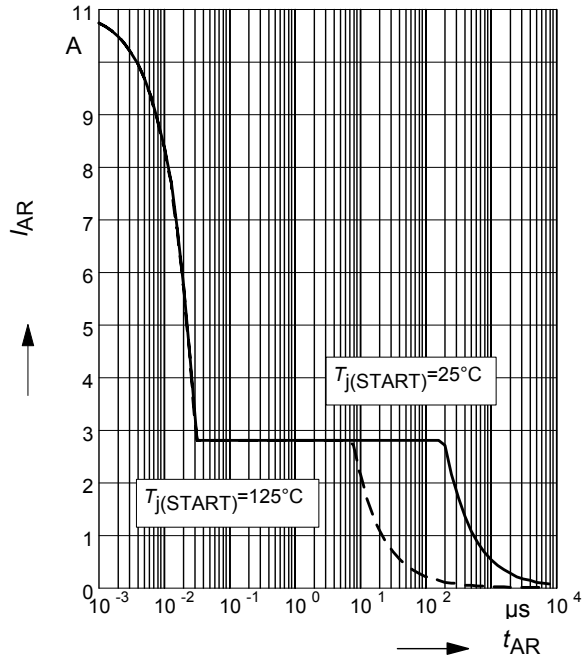
parameter: $T_j, t_p = 10 \mu s$



14 Avalanche SOA

$I_{AR} = f(t_{AR})$

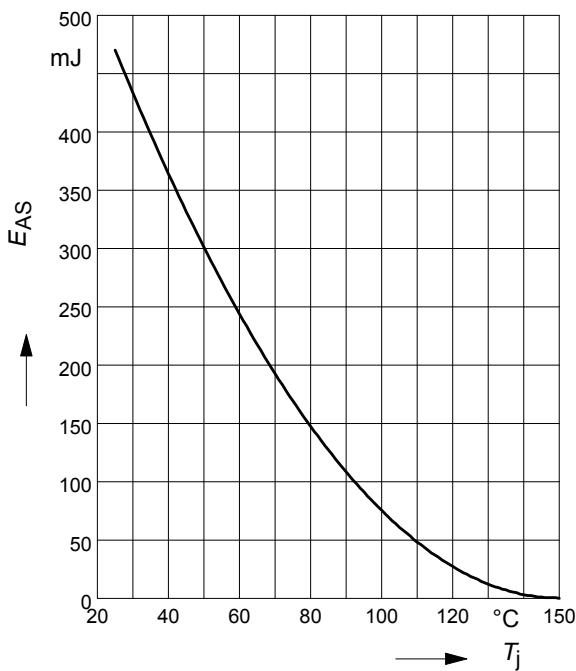
par.: $T_j \leq 150 \text{ °C}$



15 Avalanche energy

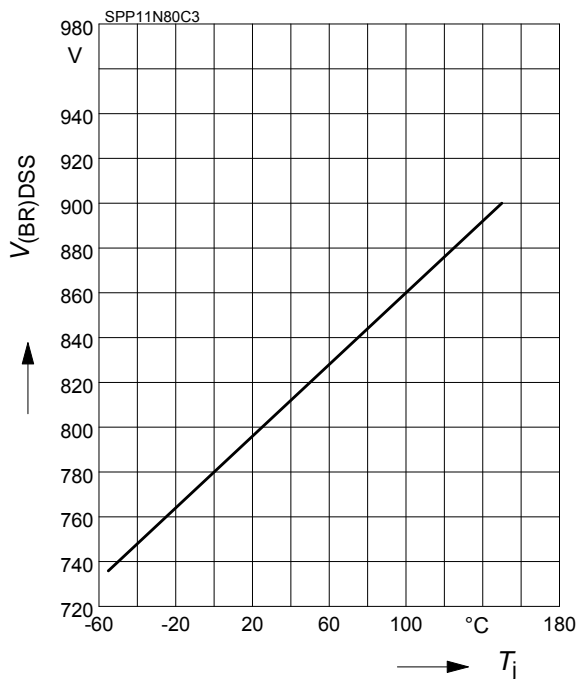
$E_{AS} = f(T_j)$

par.: $I_D = 2.2 \text{ A}, V_{DD} = 50 \text{ V}$



16 Drain-source breakdown voltage

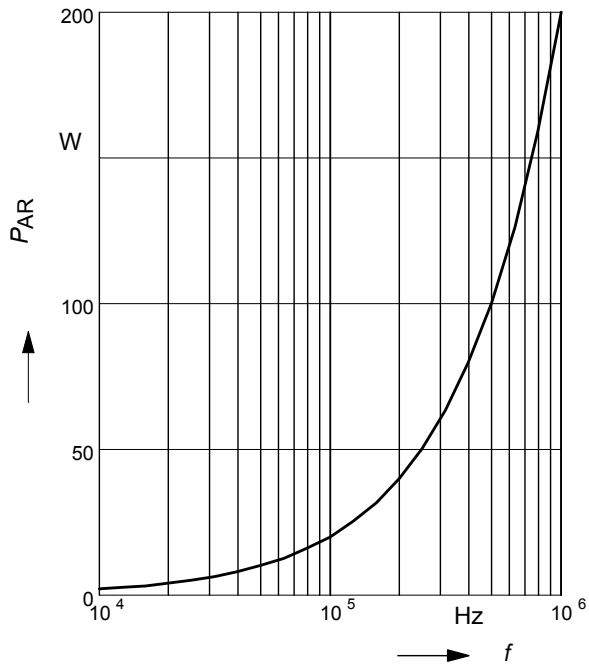
$V_{(BR)DSS} = f(T_j)$



17 Avalanche power losses

$$P_{AR} = f(f)$$

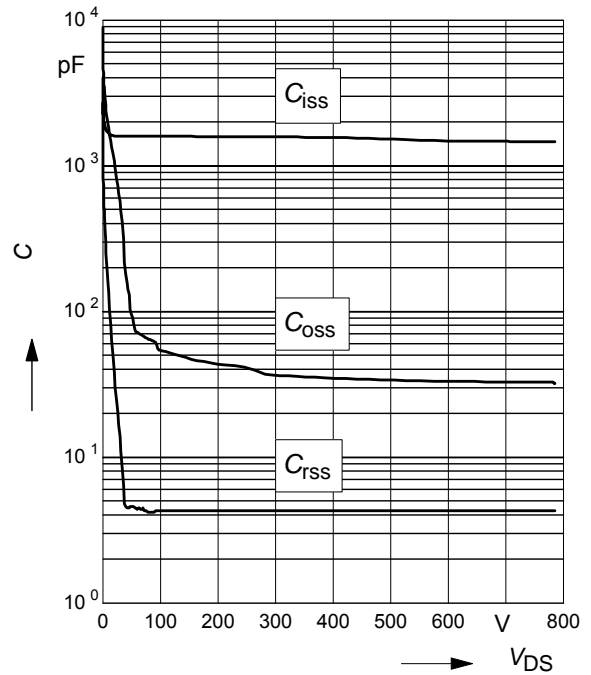
parameter: $E_{AR}=0.2\text{mJ}$



18 Typ. capacitances

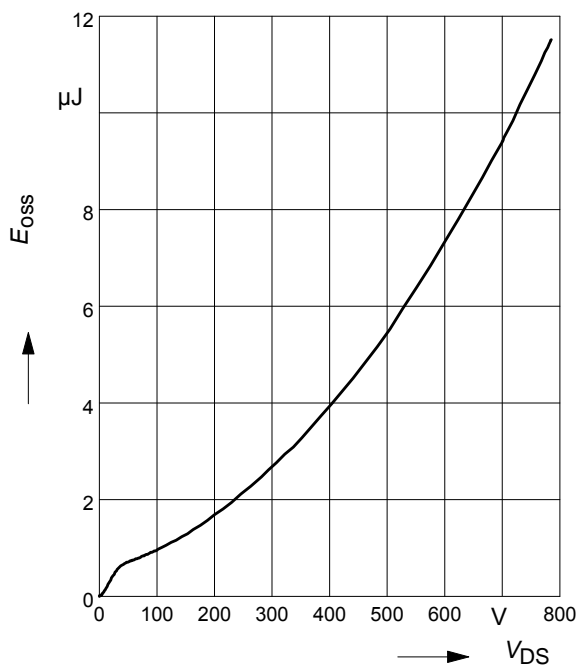
$$C = f(V_{DS})$$

parameter: $V_{GS}=0\text{V}$, $f=1\text{ MHz}$

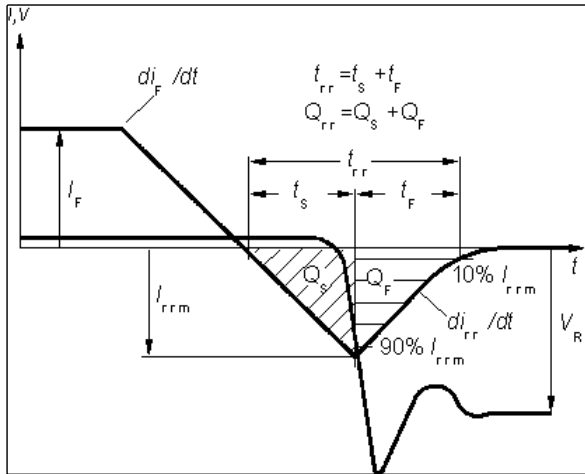


19 Typ. C_{OSS} stored energy

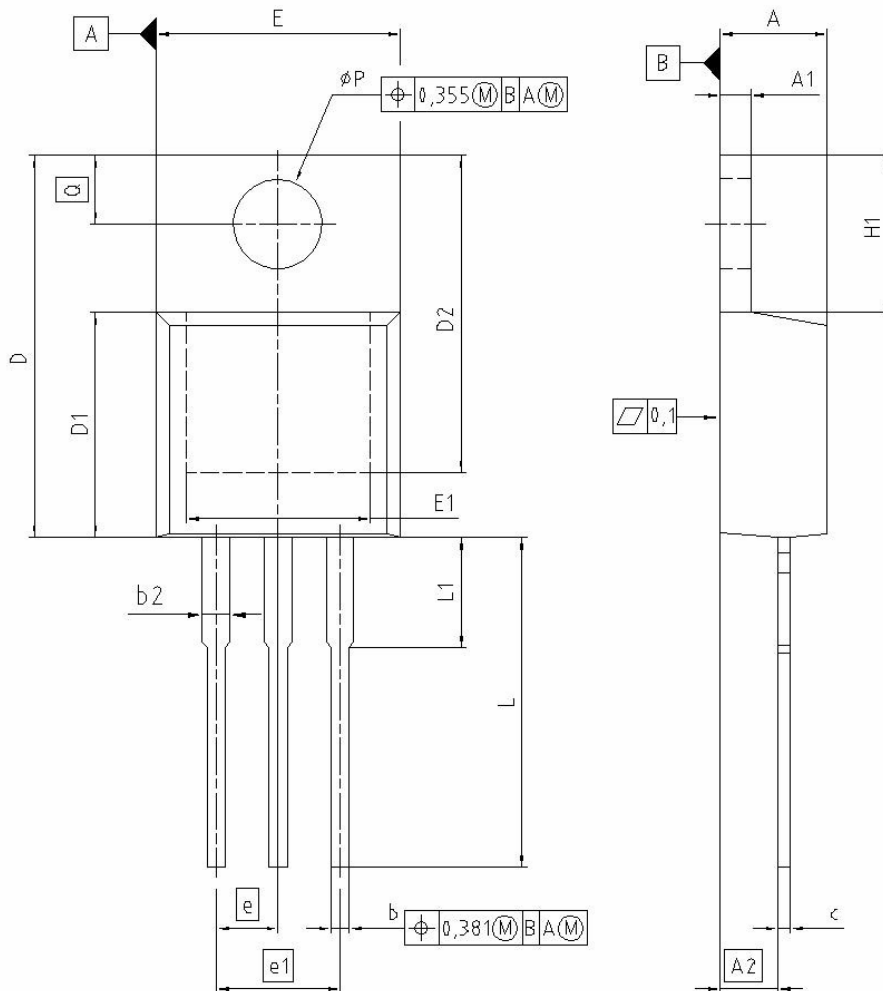
$$E_{OSS} = f(V_{DS})$$



Definition of diodes switching characteristics



PG-TO220-3-1, PG-TO220-3-21



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.300	4.572	0.169	0.180
A1	1.170	1.400	0.046	0.055
A2	2.215	2.718	0.087	0.107
b	0.650	0.864	0.026	0.034
b2	0.635	1.778	0.025	0.070
c	0.330	0.600	0.013	0.024
D	14.808	15.950	0.583	0.628
D1	8.509	9.450	0.335	0.372
D2	12.850	13.100	0.506	0.516
E	9.700	10.363	0.382	0.408
E1	6.500	8.600	0.256	0.339
e	2.540		0.100	
e1	5.080		0.200	
N	3		3	
H1	5.900	6.900	0.232	0.272
L	13.000	14.000	0.512	0.551
L1	-	4.800	-	0.189
pP	3.700	3.886	0.146	0.153
Q	2.600	3.000	0.102	0.118

REFERENCE
JEDEC TO220

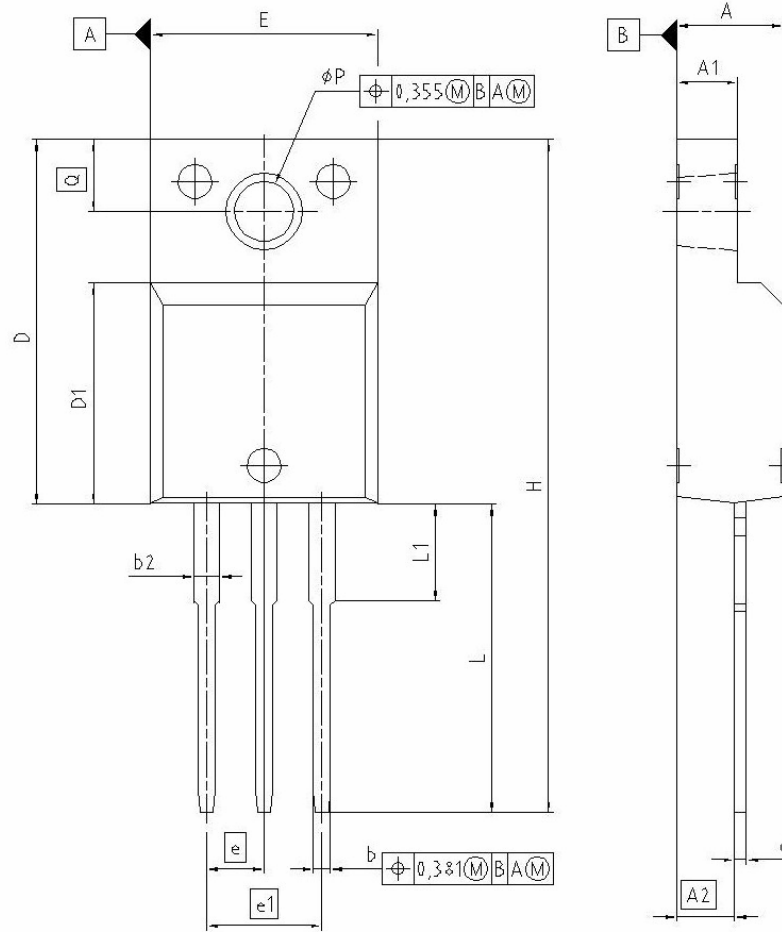
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TO220_1

PG-TO220-3-31 (FullPAK)



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.572	4.826	0.180	0.190
A1	2.573	2.827	0.101	0.111
A2	2.514	2.616	0.099	0.103
b	0.649	0.776	0.025	0.030
b2	1.143	1.509	0.045	0.059
c	0.449	0.627	0.017	0.027
D	15.863	16.117	0.624	0.634
D1	9.554	9.808	0.376	0.386
E	10.373	10.627	0.408	0.418
e	2.540		0.100	
e1	5.080		0.200	
N	3		3	
H	29.463	29.717	1.160	1.170
L	13.473	13.727	0.530	0.540
L1	3.175	3.429	0.125	0.135
eP	2.949	3.025	0.119	0.116
Q	3.149	3.251	0.124	0.128

REFERENCE
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